FIG.1

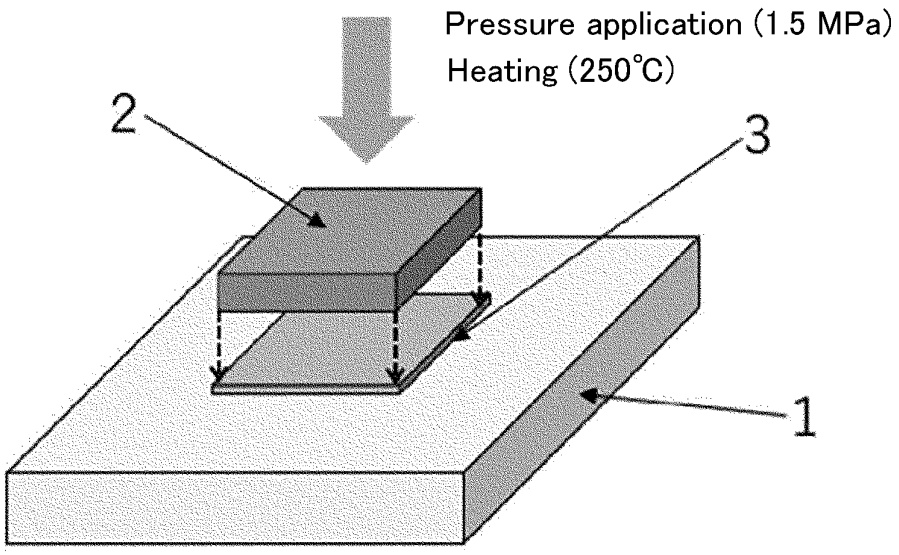
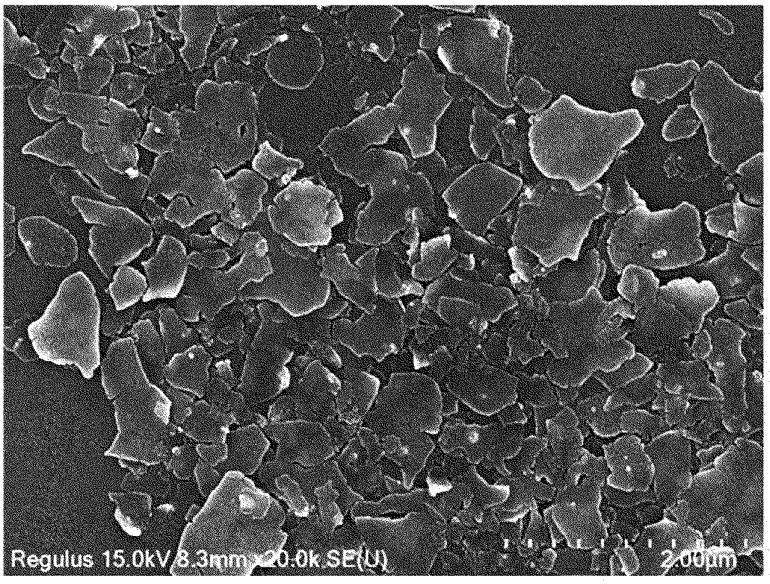


FIG.2

(a)


Regulus 15.0kV 8.3mm x20.0k SE(U)
2.00μm

(b)

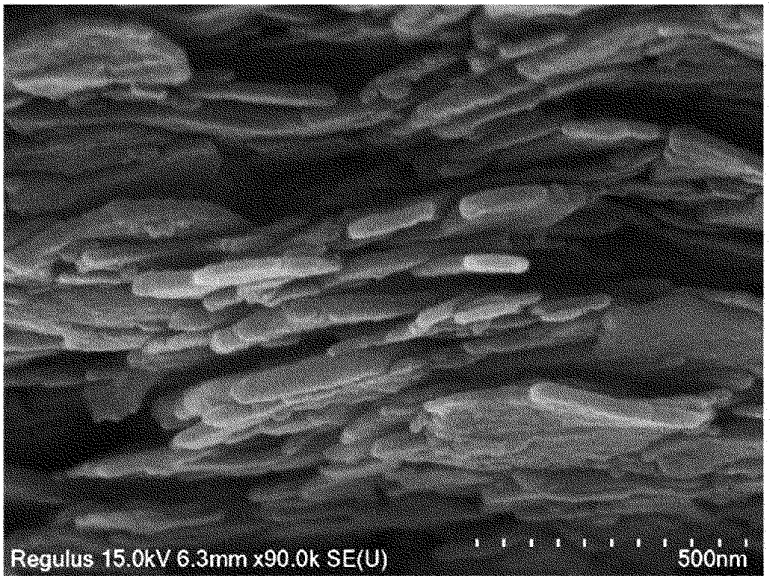

Regulus 15.0kV 6.3mm x90.0k SE(U)
500nm

FIG.3

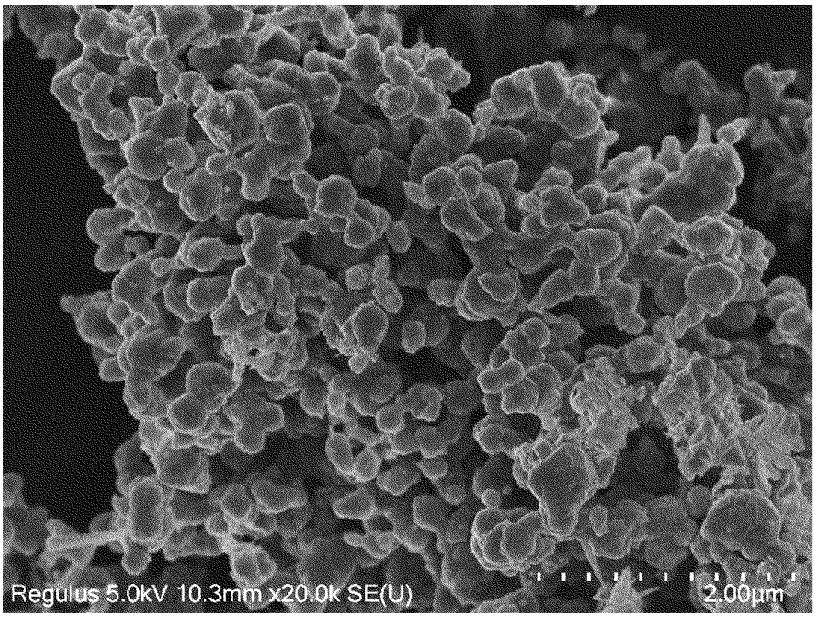
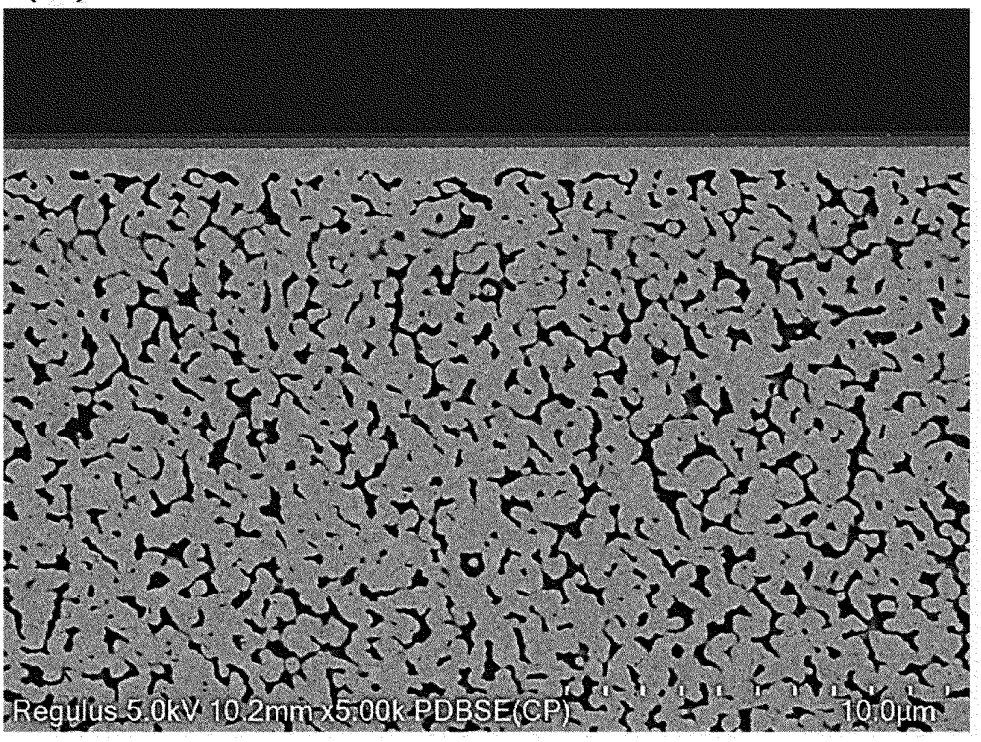


FIG.4

(a)


Regulus 5.0kV 10.2mm x5.00k PDBSE(CP)
10.0μm

(b)

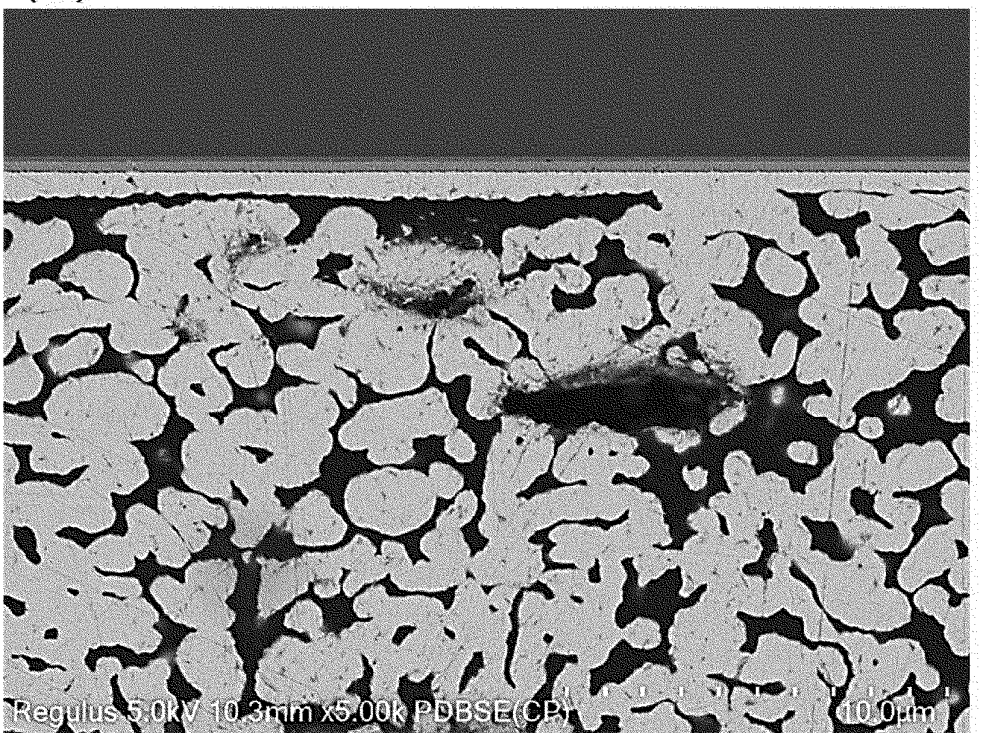
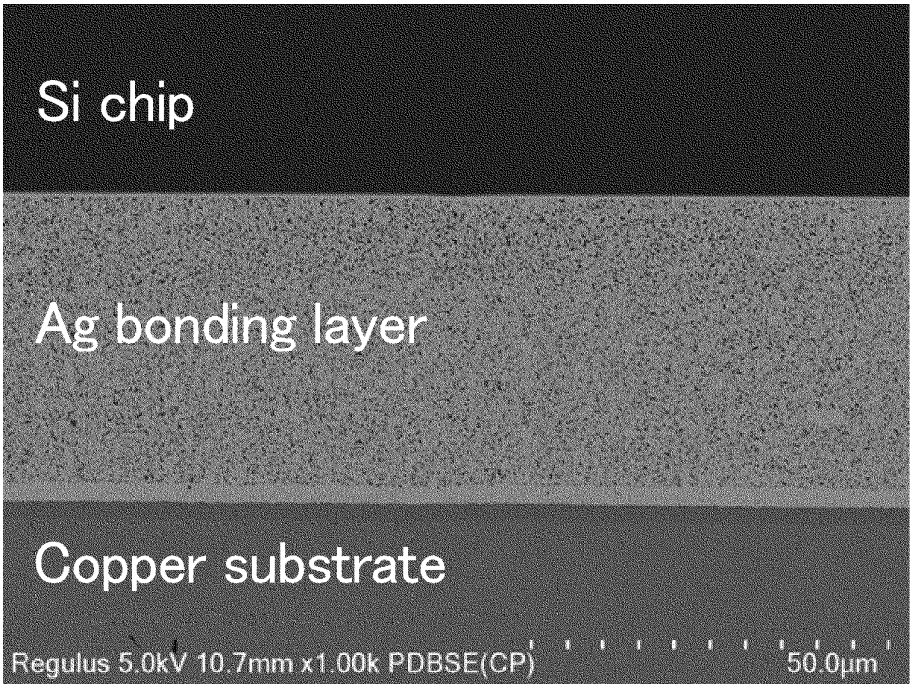

Regulus 5.0kV 10.3mm x5.00k PDBSE(CP)
10.0μm

FIG.5


Si chip
Ag bonding layer
Copper substrate
Regulus 5.0kV 10.7mm x1.00k PDBSE(CP)
50.0µm